

# Final Finishing – ENEPIG Technology

# 表面处理 – 化学镍钯金技术

## PALLAMERSE™ SMT2000 Electroless Palladium

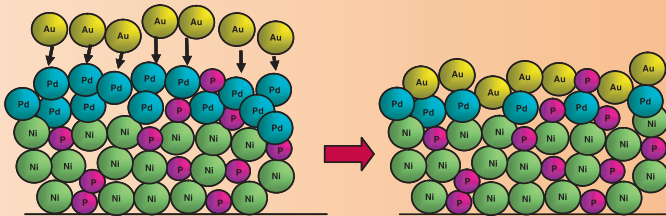
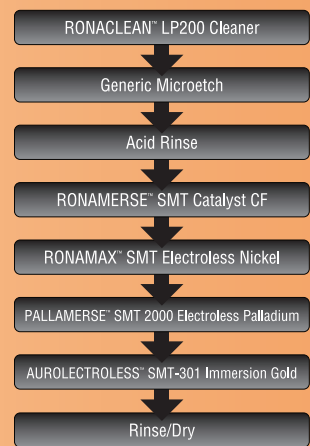
The Palladium layer protects the Nickel layer from corrosion and inhibits the phosphorous rich layer growth to provide outstanding reliability.

钯层保护镍层并抑制富磷层增生，表现出优异的焊点可靠度。

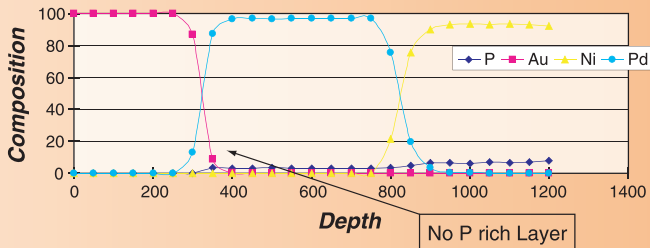
### Advantages 优点

- Electroless palladium layer prevents attack of Cu/Ni substrate  
化学钯层防止铜与镍层被攻击
- Excellent wire bondability with thin gold deposit  
配合薄金镀层表现出优越之打线接合能力
- Well buffered system and easy maintenance procedure for bath solution  
优异及简易的槽液控制系统
- Excellent selectivity of deposition eliminate outer growth problem  
高度选择性沉积
- Outstanding Pd/Au plating on both copper and nickel  
在铜及镍层有优异的钯金沉积能力

### Process 製程



Ni/Pd/Au Depth vs. Composition



	Nickel Outer Growth Issue	Fine Line Design	Ball Bonding Ability	Wire Bonding Ability	Cost	Bath Stability
<b>PAUROBOND</b> EL-Ni/EL-Pd/IM-Au	○	○	○	○	○	○
<b>ENIG</b> EL-Ni/IM-Au(Thin)	△	○	○	X	○	○
<b>ENIG</b> EL-Ni/IM-Au(Thick)	△	○	○	○	X	△
<b>Direct Au</b>	○	○	○	○	X	X
<b>Electro Ni/ Electro Au</b>	○	X	○	○	X	○

